

1A Avg.

30 Volts

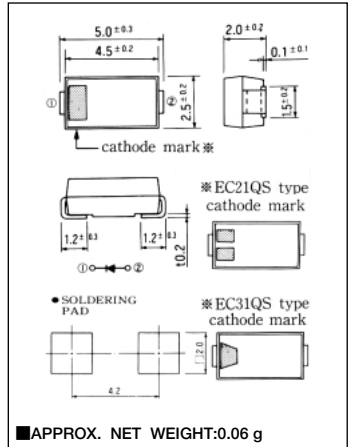
SBD

EC10LA03

■最大定格 Maximum Ratings

Item	Symbol	Conditions	Unit
くり返しピーク逆電圧 Repetitive Peak Reverse Voltage	V_{RRM}	30	V
直流順電流 Direct Forward Current	I_{DC}	直流通電 $T_a=71^{\circ}\text{C}^{*1}$	1.0 A
		$T_a=88^{\circ}\text{C}^{*2}$	1.0 A
サージ順電流 Surge Forward Current	I_{FSM}	25 50Hz正弦半波, 1サイクル, 非くり返し 50Hz Half Sine Wave, 1cycle, Non-repetitive	A
動作接合温度範囲 Operating Junction Temperature Range	T_{jw}	-40~+125	$^{\circ}\text{C}$
保存温度範囲 Storage Temperature Range	T_{stg}	-40~+125	$^{\circ}\text{C}$

■OUTLINE DRAWING(mm)



■電氣的・熱的特性 Electrical/Thermal Characteristics

Item	Symbol	Conditions	Min.	Typ.	Max.	Unit
ピーク逆電流 Peak Reverse Current	I_{RM}	$T_j=25^{\circ}\text{C}, V_{RM}=V_{RRM}$	—	—	2	mA
ピーク順電圧 Peak Forward Voltage	V_{FM}	$T_j=25^{\circ}\text{C}, I_{FM}=1\text{A}$	—	—	0.39	V
熱抵抗 Thermal Resistance	$R_{th(j-a)}$	接合部・周囲間 Junction to Ambient	Glass Epoxy Substrate Mounted ^{*1}		157	$^{\circ}\text{C}/\text{W}$
		Alumina Substrate Mounted ^{*2}		108	$^{\circ}\text{C}/\text{W}$	

*1: プリント基板実装/Glass-Epoxy Substrate mounted (Soldering Lands=2×2mm, Both Sides)
*2: アルミナ基板実装/Alumina Substrate mounted (Soldering Lands=2×2mm, Both Sides)

■定格・特性曲線

